



Material Content Data Sheet



Sales Product Name	SAK-TC387QP-160F300S AA			Issued		4. October 2018		
MA#	MA001811438							
Package	PG-LFBGA-292-11			Weight*		860.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	26.579	3.09	3.09	30871	30871
wire	noble metal	palladium	7440-05-3	0.017	0.00		20	
	non noble metal	copper	7440-50-8	1.697	0.20	0.20	1972	1992
encapsulation	organic material	carbon black	1333-86-4	0.700	0.08		813	
	plastics	epoxy resin	-	48.294	5.61		56092	
	inorganic material	silicondioxide	60676-86-0	300.961	34.96	40.65	349556	406461
substrate	inorganic material	bariumsulfate	7727-43-7	10.803	1.25		12547	
	plastics	acrylic resin	-	12.502	1.45		14521	
	inorganic material	Metal Hydroxide	-	17.115	1.99		19878	
	non noble metal	copper	7440-50-8	46.536	5.40		54050	
	inorganic material	silicondioxide	60676-86-0	54.196	6.29		62947	
	plastics	epoxy resin	-	101.170	11.75		117506	
	inorganic material	glass fibre	-	119.802	13.91	42.04	139146	420595
plating	noble metal	gold	7440-57-5	1.136	0.13		1320	
	non noble metal	nickel	7440-02-0	3.110	0.36	0.49	3612	4932
solderball	noble metal	silver	7440-22-4	3.921	0.46		4554	
	non noble metal	tin	7440-31-5	108.111	12.56	13.02	125568	130122
glue	plastics	epoxy resin	-	1.082	0.13		1257	
	noble metal	silver	7440-22-4	3.246	0.38	0.51	3770	5027
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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